

## P-Channel 30 V (D-S) MOSFET

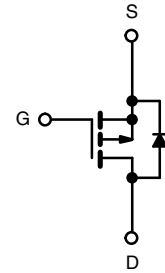
**PowerPAK® 1212-8SH**

**FEATURES**

- TrenchFET® power MOSFET
- Low thermal resistance PowerPAK® package with small size
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**
**APPLICATIONS**

- Load switch
- Adapter switch
- Notebook PC



P-Channel MOSFET

**PRODUCT SUMMARY**

|  |        |
|--|--------|
| V <sub>DS</sub> (V)                                      | -30    |
| R <sub>DS(on)</sub> max. (Ω) at V <sub>GS</sub> = -10 V  | 0.0114 |
| R <sub>DS(on)</sub> max. (Ω) at V <sub>GS</sub> = -4.5 V | 0.0200 |
| Q <sub>g</sub> typ. (nC)                                 | 24.6   |
| I <sub>D</sub> (A) <sup>e, f</sup>                       | -35    |
| Configuration  | Single |

**ORDERING INFORMATION**

|                                 |                  |
|---------------------------------|------------------|
| Package                         | PowerPAK 1212-8  |
| Lead (Pb)-free and halogen-free | SiSH129DN-T1-GE3 |

**ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

| PARAMETER  | SYMBOL                            | LIMIT                  | UNIT                  |
|--|-----------------------------------|------------------------|-----------------------|
| Drain-source voltage   | V <sub>DS</sub>                   | -30                    | V                     |
| Gate-source voltage  | V <sub>GS</sub>                   | ± 20                   |                       |
| Continuous drain current (T <sub>J</sub> = 150 °C)           | I <sub>D</sub>                    | T <sub>C</sub> = 25 °C | -35 <sup>e</sup>      |
|  |                                   | T <sub>C</sub> = 70 °C | -35 <sup>e</sup>      |
|  |                                   | T <sub>A</sub> = 25 °C | -14.4 <sup>a, b</sup> |
|  |                                   | T <sub>A</sub> = 70 °C | -11.5 <sup>a, b</sup> |
| Pulsed drain current   | I <sub>DM</sub>                   | -60                    | A                     |
| Continuous source-drain diode current                        | I <sub>S</sub>                    | T <sub>C</sub> = 25 °C |                       |
|  |                                   | T <sub>A</sub> = 25 °C | -3.2 <sup>a, b</sup>  |
| Avalanche current  | I <sub>AS</sub>                   | -25                    | mJ                    |
| Single pulse avalanche energy                                | E <sub>AS</sub>                   | 31.25                  |                       |
| Maximum power dissipation                                    | P <sub>D</sub>                    | T <sub>C</sub> = 25 °C | 52.1                  |
|  |                                   | T <sub>C</sub> = 70 °C | 3.3                   |
|  |                                   | T <sub>A</sub> = 25 °C | 3.8 <sup>a, b</sup>   |
|  |                                   | T <sub>A</sub> = 70 °C | 2.4 <sup>a, b</sup>   |
| Operating junction and storage temperature range             | T <sub>J</sub> , T <sub>stg</sub> | -50 to +150            | °C                    |
| Soldering recommendations (peak temperature) <sup>c, d</sup> |                                   | 260                    |                       |

**Notes**

- Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257)). The PowerPAK 1212-8SH is a leadless package within the PowerPAK 1212-8 package family. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Package limited
- Based on T<sub>C</sub> = 25 °C



| THERMAL RESISTANCE RATINGS                  |               |            |         |         |      |  |
|---|---------------|------------|---------|---------|------|--|
| PARAMETER                                   |               | SYMBOL     | TYPICAL | MAXIMUM | UNIT |  |
| Maximum junction-to-ambient <sup>a, b</sup> | $t \leq 10$ s | $R_{thJA}$ | 26      | 33      | °C/W |  |
| Maximum junction-to-case (drain)            | Steady state  | $R_{thJC}$ | 1.9     | 2.4     |      |  |

**Notes**

- a. Surface mounted on 1" x 1" FR4 board  
b. Maximum under steady state conditions is 81 °C/W

| SPECIFICATIONS ( $T_J = 25$ °C, unless otherwise noted) |                         |   |      |        |                  |          |
|---|-------------------------|---|------|--------|------------------|----------|
| PARAMETER   | SYMBOL                  | TEST CONDITIONS   | MIN. | TYP.   | MAX.             | UNIT     |
| <b>Static</b>   |                         |   |      |        |                  |          |
| Drain-source breakdown voltage                          | $V_{DS}$                | $V_{GS} = 0$ V, $I_D = -250$ $\mu$ A  | -30  | -      | -                | V        |
| $V_{DS}$ temperature coefficient                        | $\Delta V_{DS}/T_J$     | $I_D = -250$ $\mu$ A  | -    | -20    | -                | mV/°C    |
| $V_{GS(th)}$ temperature coefficient                    | $\Delta V_{GS(th)}/T_J$ |   | -    | 5      | -                |          |
| Gate-source threshold voltage                           | $V_{GS(th)}$            | $V_{DS} = V_{GS}$ , $I_D = -250$ $\mu$ A  | -1.5 | -      | -2.8             | V        |
| Gate-source leakage                                     | $I_{GSS}$               | $V_{DS} = 0$ V, $V_{GS} = \pm 20$ V   | -    | -      | $\pm 100$        | nA       |
| Zero gate voltage drain current                         | $I_{DSS}$               | $V_{DS} = -30$ V, $V_{GS} = 0$ V  | -    | -      | -1               | $\mu$ A  |
|   |                         | $V_{DS} = -30$ V, $V_{GS} = 0$ V, $T_J = 55$ °C   | -    | -      | -10              |          |
| On-state drain current <sup>a</sup>                     | $I_{D(on)}$             | $V_{DS} \leq -5$ V, $V_{GS} = -10$ V  | -20  | -      | -                | A        |
| Drain-source on-state resistance <sup>a</sup>           | $R_{DS(on)}$            | $V_{GS} = -10$ V, $I_D = -14.4$ A   | -    | 0.0095 | 0.0114           | $\Omega$ |
|   |                         | $V_{GS} = -4.5$ V, $I_D = -11.5$ A  | -    | 0.0160 | 0.0200           |          |
| Forward transconductance <sup>a</sup>                   | $g_{fs}$                | $V_{DS} = -15$ V, $I_D = -14.4$ A   | -    | 37     | -                | S        |
| <b>Dynamic <sup>b</sup></b>                             |                         |   |      |        |                  |          |
| Input capacitance                                       | $C_{iss}$               | $V_{DS} = -15$ V, $V_{GS} = 0$ V, $f = 1$ MHz   | -    | 2230   | 3345             | pF       |
| Output capacitance                                      | $C_{oss}$               |   | -    | 385    | 578              |          |
| Reverse transfer capacitance                            | $C_{rss}$               |   | -    | 322    | -                |          |
| Total gate charge                                       | $Q_g$                   | $V_{DS} = -15$ V, $V_{GS} = -10$ V, $I_D = -14.4$ A   | -    | 47.5   | 71               | nC       |
|   |                         | $V_{DS} = -15$ V, $V_{GS} = -4.5$ V, $I_D = -14.4$ A  | -    | 24.6   | 37               |          |
| Gate-source charge                                      | $Q_{gs}$                | $f = 1$ MHz   | -    | 7.7    | -                | nA       |
| Gate-drain charge                                       | $Q_{gd}$                |   | -    | 12     | -                |          |
| Gate resistance   | $R_g$                   |   | 0.4  | 1.8    | 3.6              |          |
| Turn-on delay time                                      | $t_{d(on)}$             | $V_{DD} = -15$ V, $R_L = 1.5$ $\Omega$<br>$I_D \cong -10$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ $\Omega$ | -    | 50     | 75               | ns       |
| Rise time   | $t_r$                   |   | -    | 43     | 65               |          |
| Turn-off delay time                                     | $t_{d(off)}$            |   | -    | 30     | 45               |          |
| Fall time   | $t_f$                   |   | -    | 14     | 21               |          |
| Turn-on delay time                                      | $t_{d(on)}$             | $V_{DD} = -15$ V, $R_L = 1.5$ $\Omega$<br>$I_D \cong -10$ A, $V_{GEN} = -10$ V, $R_g = 1$ $\Omega$  | -    | 14     | 21               | ns       |
| Rise time   | $t_r$                   |   | -    | 9      | 18               |          |
| Turn-off delay time                                     | $t_{d(off)}$            |   | -    | 36     | 54               |          |
| Fall time   | $t_f$                   |   | -    | 10     | 20               |          |
| <b>Drain-Source Body Diode Characteristics</b>          |                         |   |      |        |                  |          |
| Continuous source-drain diode current                   | $I_S$                   | $T_C = 25$ °C   | -    | -      | -35 <sup>e</sup> | A        |
| Pulse diode forward current <sup>a</sup>                | $I_{SM}$                |   | -    | -      | -60              |          |
| Body diode voltage                                      | $V_{SD}$                | $I_F = -10$ A   | -    | -0.8   | -1.2             | V        |
| Body diode reverse recovery time                        | $t_{rr}$                | $I_F = -10$ A, $di/dt = 100$ A/ $\mu$ s,<br>$T_J = 25$ °C   | -    | 31     | 47               | ns       |
| Body diode reverse recovery charge                      | $Q_{rr}$                |   | -    | 30     | 45               | nC       |
| Reverse recovery fall time                              | $t_a$                   |   | -    | 15     | -                | ns       |
| Reverse recovery rise time                              | $t_b$                   |   | -    | 16     | -                |          |

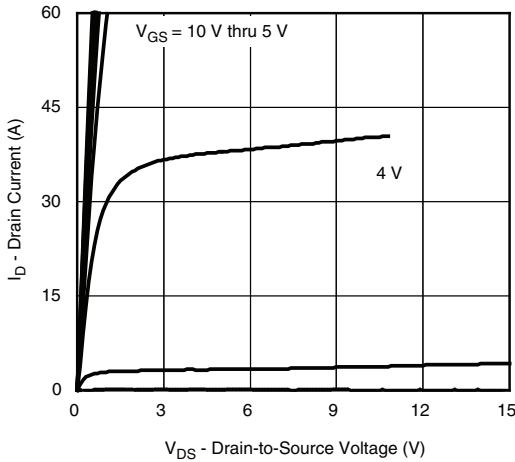
**Notes**

- a. Pulse test: pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %  
b. Guaranteed by design, not subject to production testing

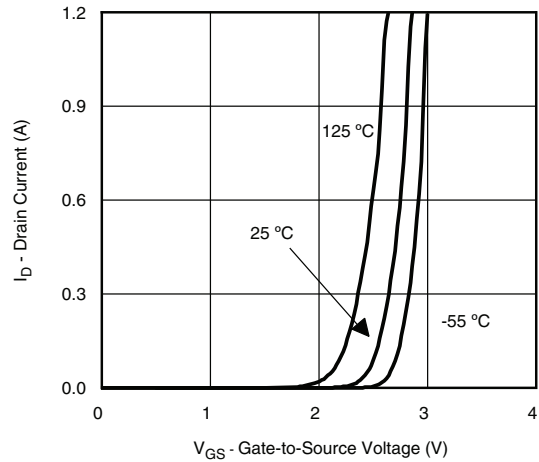
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



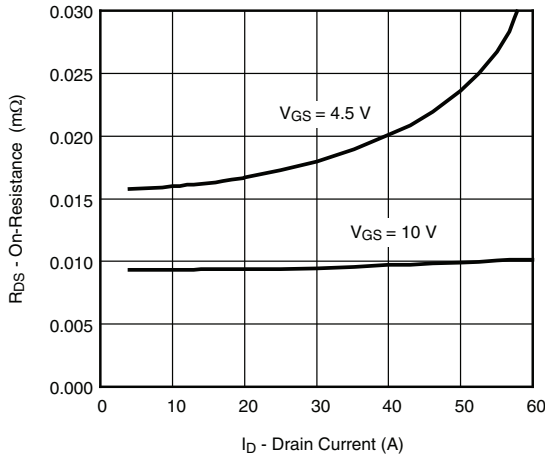
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



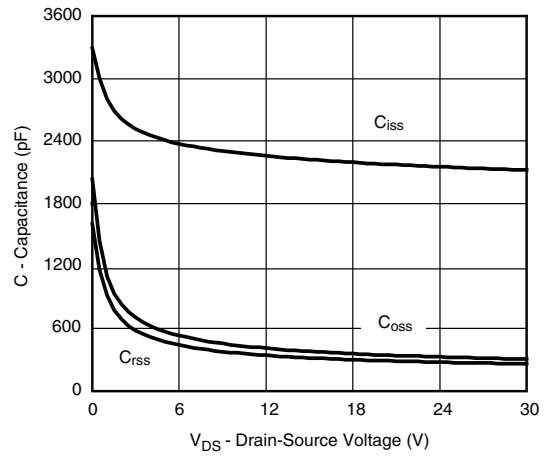
Output Characteristics



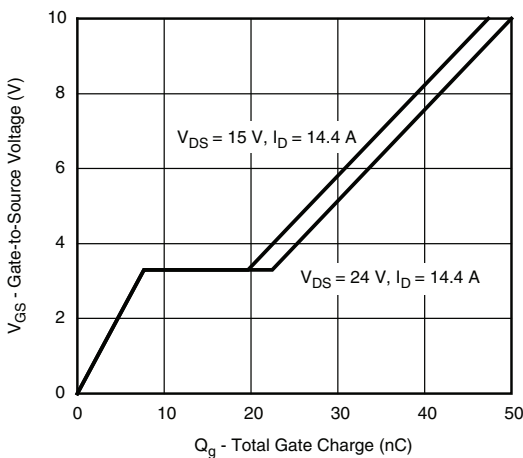
Transfer Characteristics



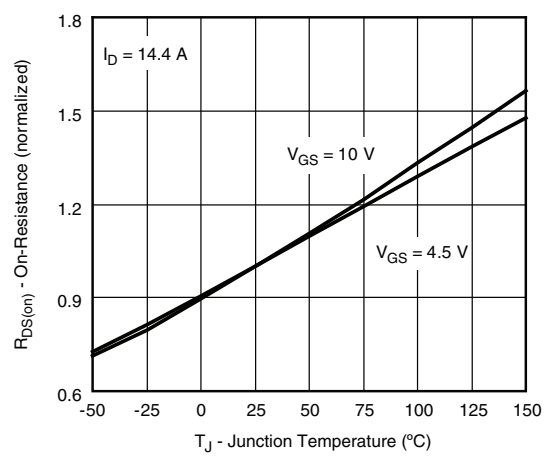
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



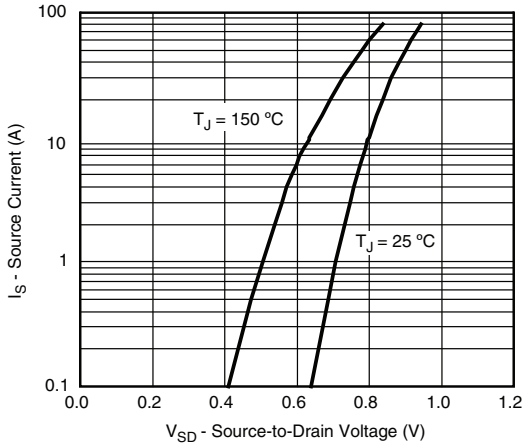
Gate Charge



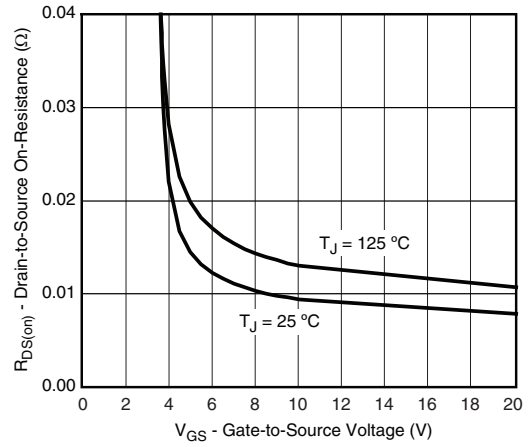
On-Resistance vs. Junction Temperature



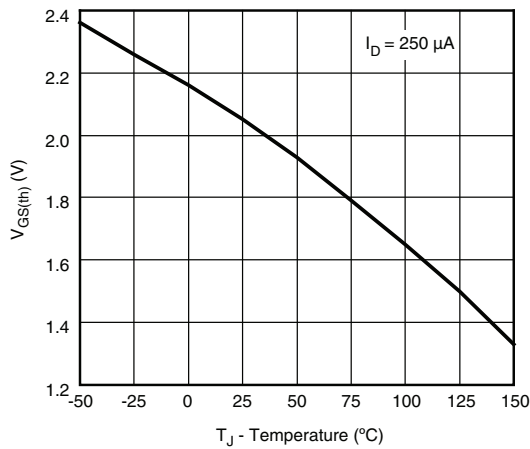
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



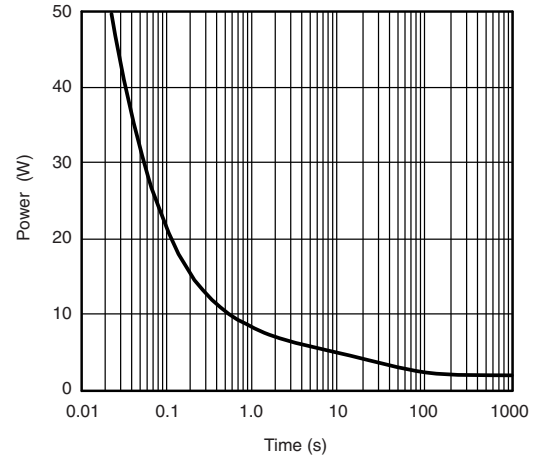
Source-Drain Diode Forward Voltage



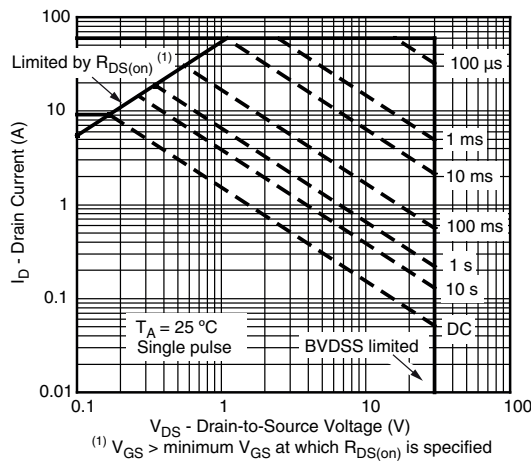
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



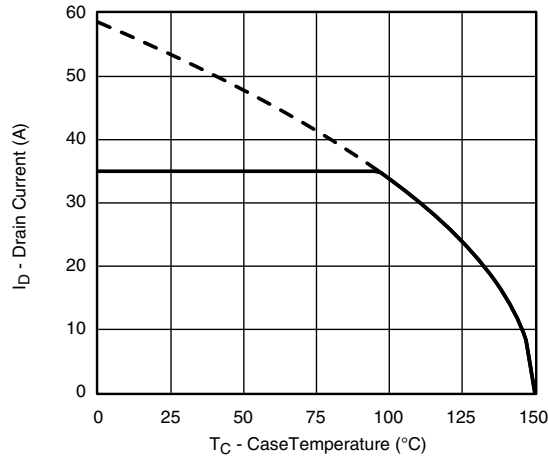
Single Pulse Power, Junction-to-Ambient



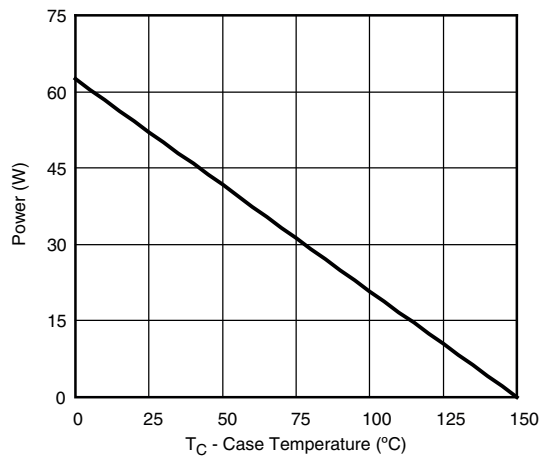
Safe Operating Area, Junction-to-Ambient



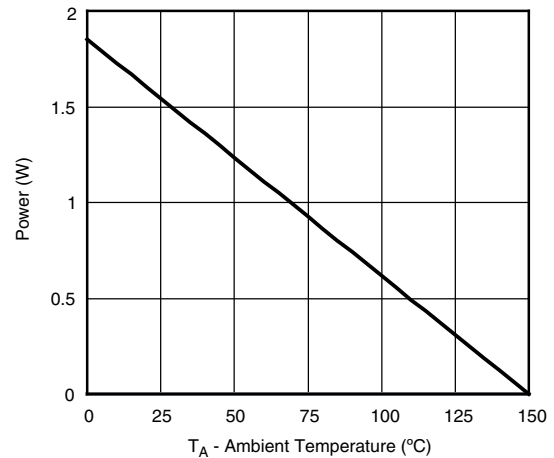
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating <sup>a</sup>**



**Power, Junction-to-Case**



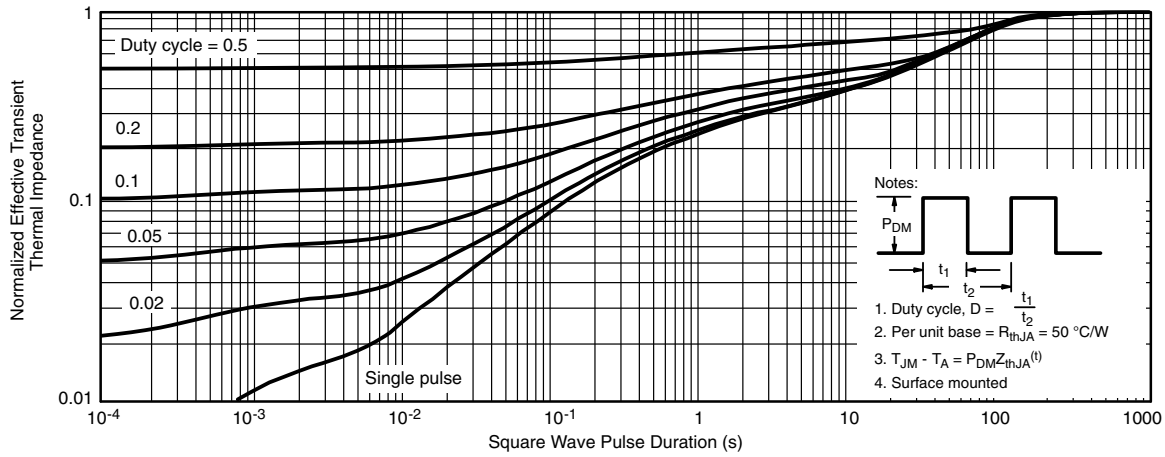
**Power, Junction-to-Ambient**

**Note**

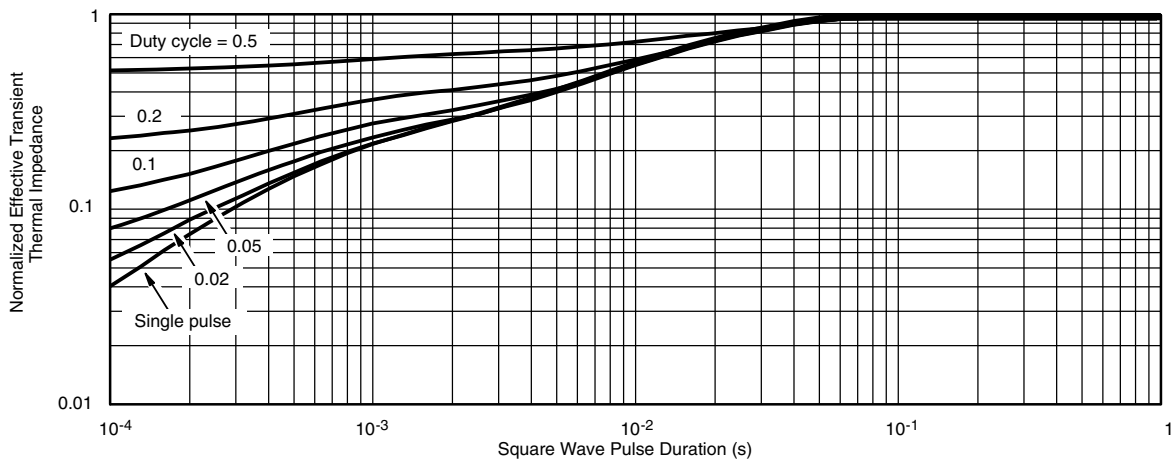
- a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

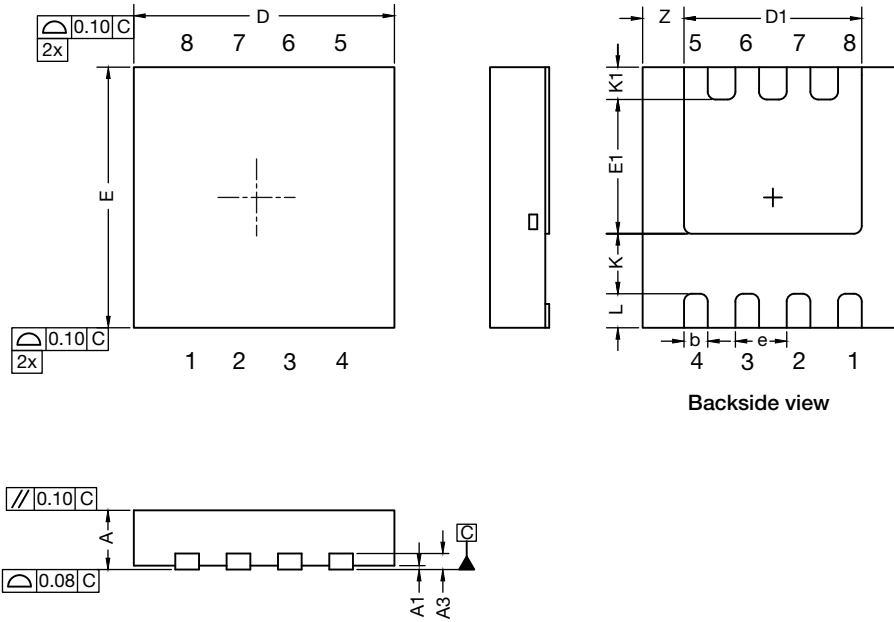


Normalized Thermal Transient Impedance, Junction-to-Case

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PowerPAK® 1212-SWLH



| DIM. | MILLIMETERS |      |      | INCHES     |       |       |
|------|-------------|------|------|------------|-------|-------|
|      | MIN.        | NOM. | MAX. | MIN.       | NOM.  | MAX.  |
| A    | 0.82        | 0.90 | 0.98 | 0.032      | 0.035 | 0.038 |
| A1   | 0           | -    | 0.05 | 0          | -     | 0.002 |
| A3   | 0.20 ref.   |      |      | 0.008 ref. |       |       |
| b    | 0.30 BSC    |      |      | 0.012 BSC  |       |       |
| D    | 3.30 BSC    |      |      | 0.130 BSC  |       |       |
| D1   | 2.15        | 2.25 | 2.35 | 0.084      | 0.088 | 0.092 |
| E    | 3.30 BSC    |      |      | 0.130 BSC  |       |       |
| E1   | 1.60        | 1.70 | 1.80 | 0.063      | 0.067 | 0.071 |
| e    | 0.65 BSC    |      |      | 0.026 BSC  |       |       |
| K    | 0.76 typ.   |      |      | 0.030 typ. |       |       |
| K1   | 0.41 typ.   |      |      | 0.016 typ. |       |       |
| L    | 0.43 BSC    |      |      | 0.017 BSC  |       |       |
| Z    | 0.525 typ.  |      |      | 0.021 typ. |       |       |

ECN: C18-0001-Rev. A, 15-Jan-18  
 DWG: 6062



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- Поставка более 17-ти миллионов наименований электронных компонентов;
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- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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